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(54) **SOUND PICKUP DEVICE DAMPING  
STRUCTURE AND SOUND PICKUP  
APPARATUS**

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(57) **ABSTRACT**

A sound pickup device damping structure and a sound pickup apparatus, the sound pickup device damping structure includes: a housing, including a side wall and a peripheral wall connected with the side wall; a circuit board, fixedly connected with the peripheral wall, wherein the circuit board and the side wall and the peripheral wall enclose to form an accommodating chamber; at least one sound pickup component, located in the accommodating chamber and electrically connected with the circuit board; and a first damping layer, disposed between the side wall and the sound pickup component; wherein a second sound pickup hole in the side wall, a hole channel in the first damping layer and a first sound pickup hole disposed in the sound pickup component are communicated with each other.

